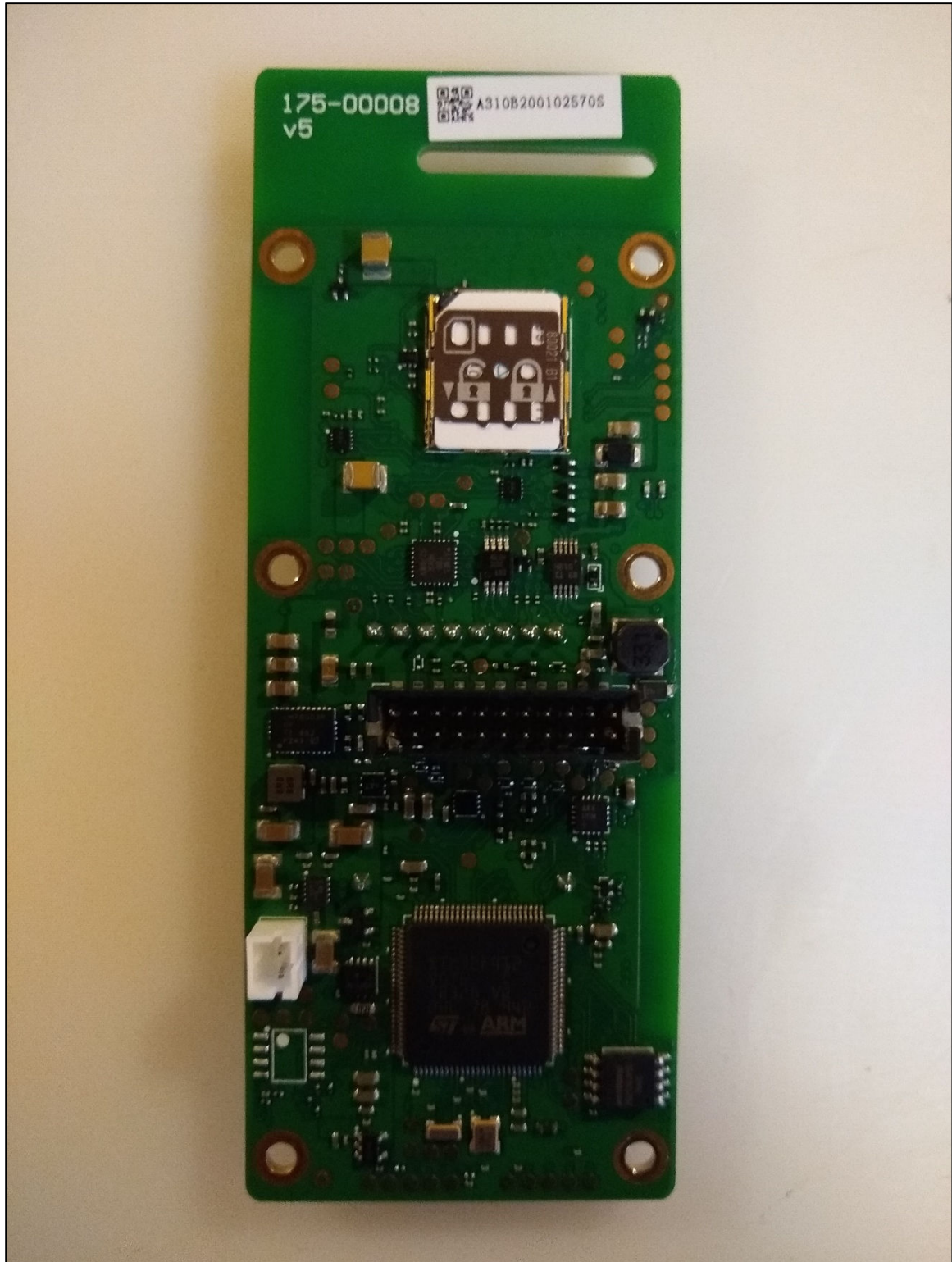
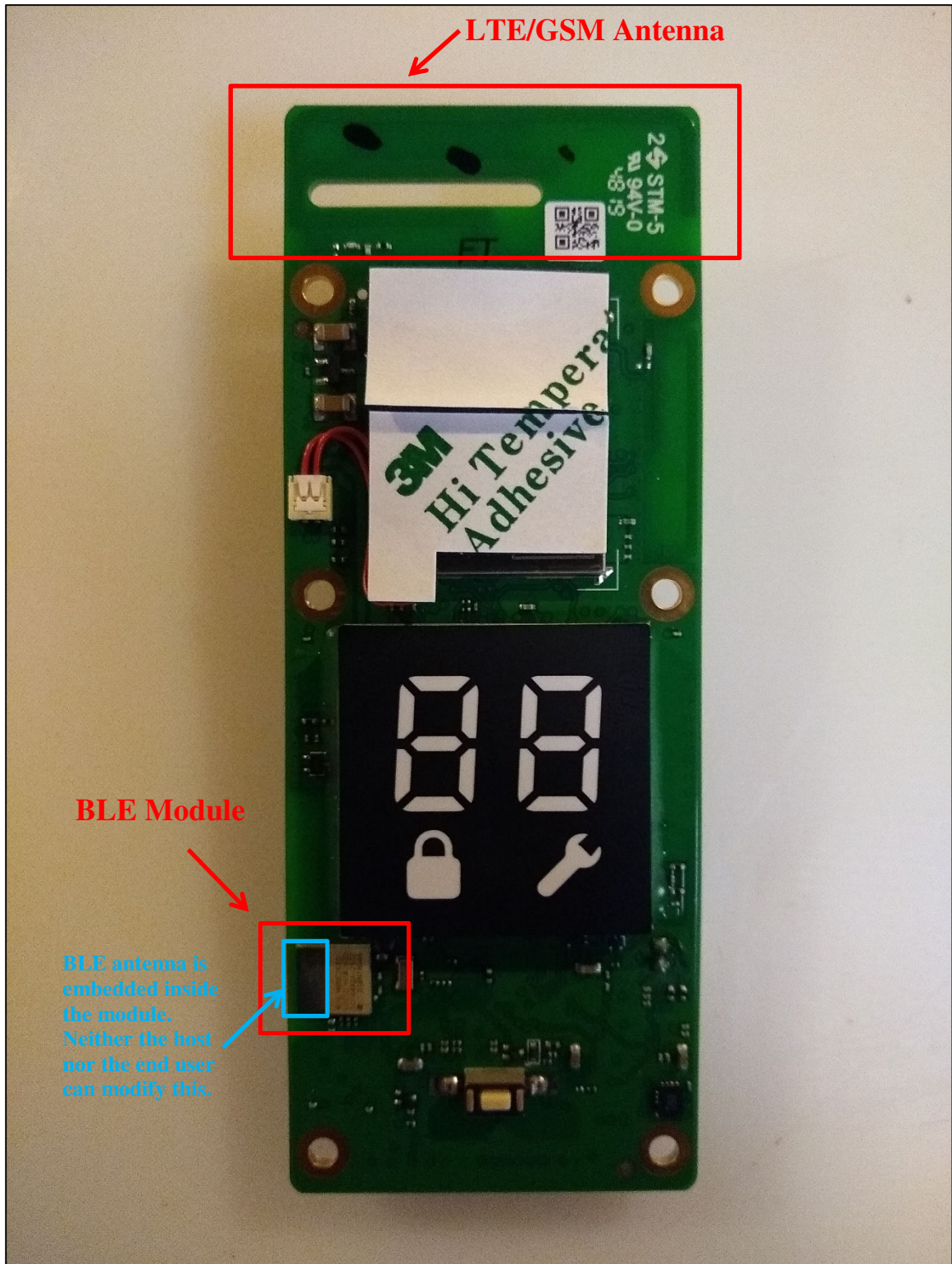


Photograph 1. Outer Cover Removed



Photograph 2. PCB – Back Side



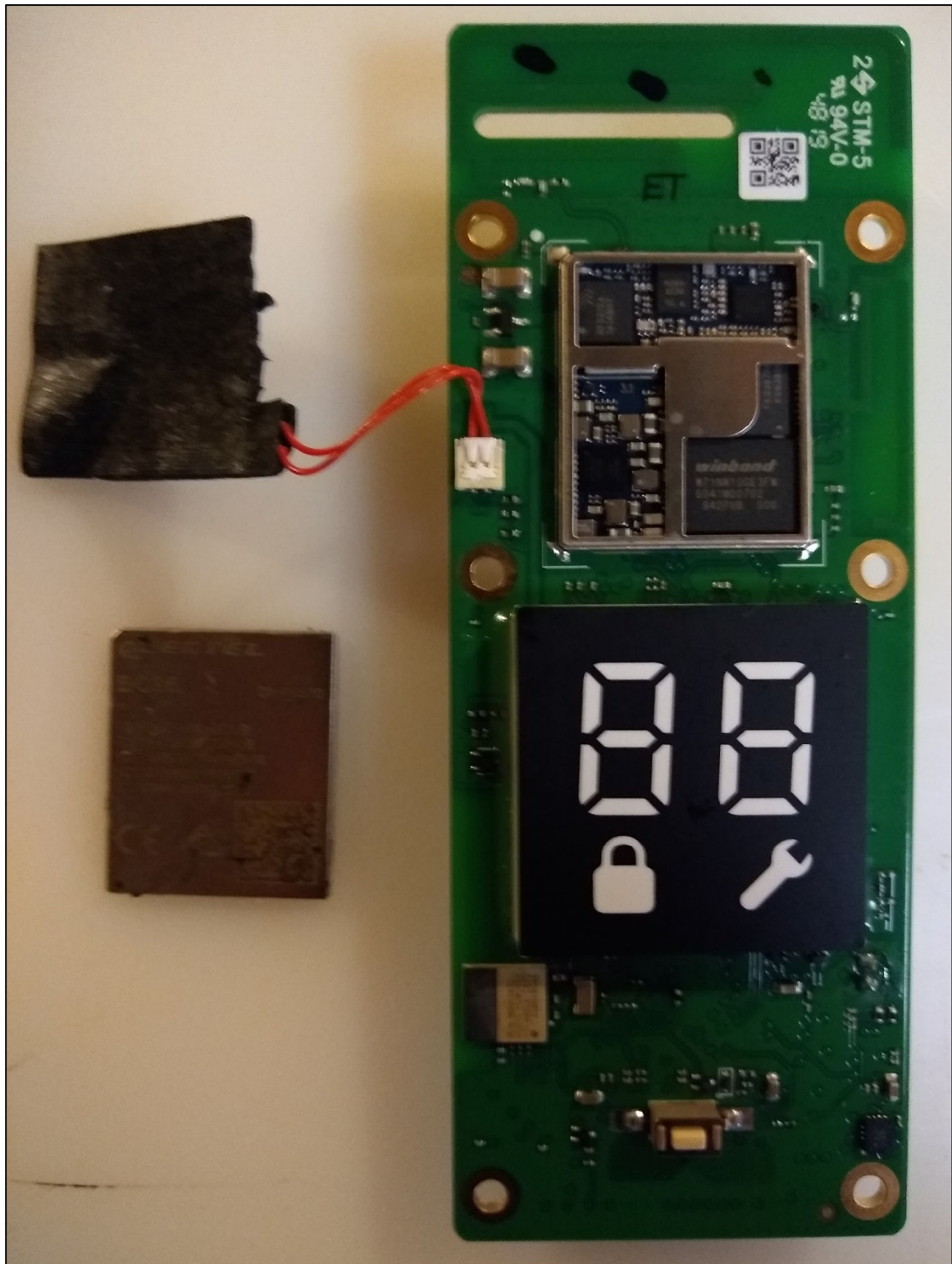


Photograph 3. PCB – Front Side

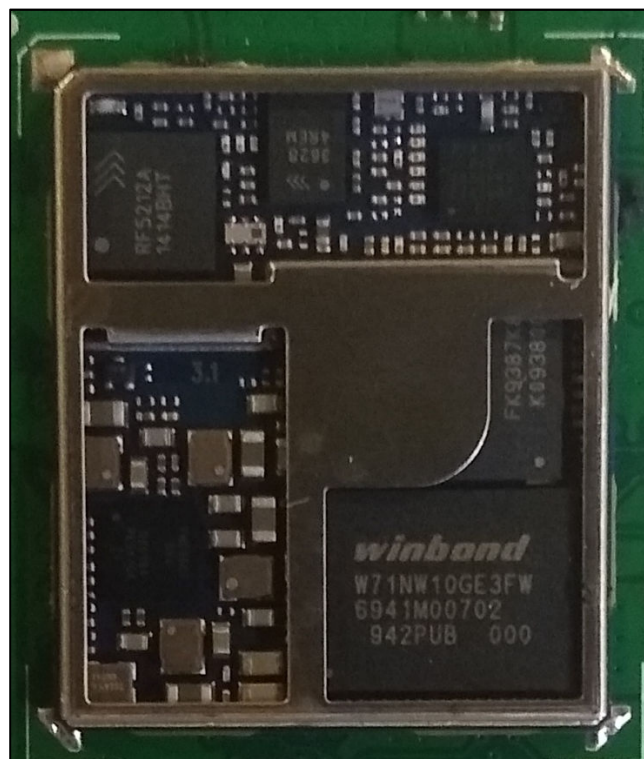


Photograph 4. PCB – Heat sensor removed to show Quectel BG96-MC module.





Photograph 5. Quectel BG96-MC module shield cover removed.



Photograph 6. Quectel BG96-MC module close-up.



Photograph 7. BLE module close-up.



Photograph 8. ARM processor close-up.